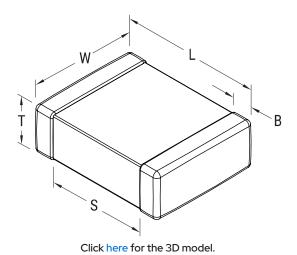


C1812X331KHRACTU

Specifications

Aliases (C1812X331KHRAC7800) SMD Comm X7R HV Flex, Ceramic, 330 pF, 10%, 3,000 VDC, X7R, SMD, MLCC, FT-CAP, Temperature Stable, 1812, 2.3 mm



General Information	
Series	SMD Comm X7R HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Temperature Stable
Features	FT-CAP, Temperature Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	95 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1812
L	4.5mm +/-0.4mm
W	3.2mm +/-0.3mm
Т	1mm +/-0.10mm
S	2.3mm MIN
В	0.7mm +/-0.35mm
D	0.711111 - 7 0.3311111

Packaging Specifications	
В	0.7mm +/-0.35mm
S	2.3mm MIN
Т	1mm +/-0.10mm
VV	3.211111 +/ -0.311111

M T	Capacitance	330 pF
	Measurement Condition	1 kHz 1.0Vrms
	Tolerance	10%
	Voltage DC	3000 VDC
	Dielectric Withstanding Voltage	3,600 VDC
	Temperature Range	-55/+125°C
	Temp. Coefficient	X7R
	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
	Dissipation Factor	2.5%1kHz1.0Vrms
	Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
	Insulation Resistance	100 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Generated 08/19/2025 © 2006 - 2025 YAGEO